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Preface

Embedded systems, i.e., computers inside products, have been adopted widely in many domains, including traditional control systems, medical instruments, wired and wireless communication devices, aerospace equipment, human-computer interfaces, and sensor networks. Two significant trends have recently been observed due to the increasing computation power and communication bandwidth. The first is that embedded systems are getting connected and are cooperating as distributed systems. The other is the extensive software in middleware and embedded applications. These trends are apparent in academic and industrial research and in the papers submitted to the International Conference on Embedded Software and Systems.

The 3rd International Conference on Embedded Software and Systems (ICESS 2007), to be held in Daegu, Republic of Korea, on May 14-16, aims to advance embedded software and systems research, development, and design competence, and to enhance international communication and collaboration. It consists of the traditional core area of embedded systems infrastructure in architecture, software, hardware, real-time computing, and testing and verification, as well as additional areas of special emphasis: pervasive/ubiquitous computing and sensor networks, HW/SW co-design and SoC, wireless communications, power-aware computing, security and dependability, and multimedia and HCI. In addition, tutorial sessions on the broad fields of embedded computing, a panel discussion session and keynote addresses are included in the conference. Based on the 387 submitted manuscripts and the 77 accepted papers, we expect that the forum will be full of high quality presentations and productive discussions.

ICESS 2007 has been made possible by the hard work of a number of people, to whom we are very grateful. They include the members of the organization committees and the vice chairs of the technical tracks in the technical program committee. Recognition is warranted for the commendable job of all members of the technical program committee, who, in the short paper reviewing period, have accomplished the significant workload of evaluating, on average, 9 papers and providing constructive comments.

We are particularly thankful to Laurence T. Yang for his guidance and effort in continuing the ICESS series. In addition, we thank all authors who submitted their outstanding work; without them the conference would not have been possible. Finally, we gratefully acknowledge the support from our sponsors.

April 2007 Yann-Hang Lee and Heung Nam Kim

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Organizers

ICESS-07 was organized by the Institute of Embedded Engineering of Korea (IEMEK).

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Table of Contents

Track 1: Embedded Architecture

Track 2: Embedded Hardware

Track 3: Embedded Software

Track 4: HW-SW Co-design and SoC

Track 5: Multimedia and HCI

Track 6: Pervasive/Ubiquitos Computing and Sensor Network:

Track 7: Power-Aware Computing

Track 8: Real-Time Systems

Track 9: Security and Dependability

Track 10: Wireless Communication